

## Features

- Surface Mount Package Ideally Suited for Automated Insertion
- Very Low Leakage Current
- **Lead Free By Design/RoHS Compliant (Note 1)**
- **"Green" Device (Note 4 and 5)**

## Mechanical Data

- Case: SOT-563
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminal Connections: See Diagram
- Terminals: Finish — Matte Tin annealed over Alloy 42 leadframe. Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 2
- Ordering Information: See Page 2
- Weight: 0.003 grams (approximate)

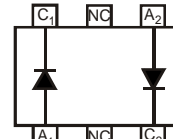


TOP VIEW



BOTTOM VIEW

SOT-563


 TOP VIEW  
Internal Schematic

## Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	$V_{RRM}$	85	V
Working Peak Reverse Voltage	$V_{RWM}$		
DC Blocking Voltage	$V_R$		
RMS Reverse Voltage	$V_{R(RMS)}$	60	V
Forward Continuous Current (Note 2)	$I_{FM}$	215	mA
Repetitive Peak Forward Current	$I_{FRM}$	500	mA
Non-Repetitive Peak Forward Surge Current	$I_{FSM}$	@ $t = 1.0\mu\text{s}$	4.0
		@ $t = 1.0\text{ms}$	1.0
		@ $t = 1.0\text{s}$	0.5

## Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 2)	$P_D$	150	mW
Thermal Resistance Junction to Ambient Air (Note 2)	$R_{\theta JA}$	833	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-65 to +150	$^\circ\text{C}$

## Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 3)	$V_{(BR)R}$	85	—	—	V	$I_R = 100\mu\text{A}$
Forward Voltage	$V_{FM}$	—	—	0.90	V	$I_F = 1.0\text{mA}$
				1.0		$I_F = 10\text{mA}$
				1.1		$I_F = 50\text{mA}$
				1.25		$I_F = 150\text{mA}$
Leakage Current (Note 3)	$I_{RM}$	—	—	5.0	nA	$V_R = 75\text{V}$
				80		$V_R = 75\text{V}, T_J = 150^\circ\text{C}$
Total Capacitance	$C_T$	—	2	—	pF	$V_R = 0, f = 1.0\text{MHz}$
Reverse Recovery Time	$t_{rr}$	—	—	3.0	$\mu\text{s}$	$I_F = I_R = 10\text{mA}, I_{rr} = 0.1 \times I_R, R_L = 100\Omega$

- Notes:
1. No purposefully added lead.
  2. Part mounted on FR-4 PC board with recommended pad layout, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
  3. Short duration pulse test used to minimize self-heating effect.
  4. Diodes Inc.'s "Green" policy can be found on our website at [http://www.diodes.com/products/lead\\_free/index.php](http://www.diodes.com/products/lead_free/index.php).
  5. Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date Code UO are built with Non-Green Molding Compound and may contain Halogens or  $\text{Sb}_2\text{O}_3$  Fire Retardants.

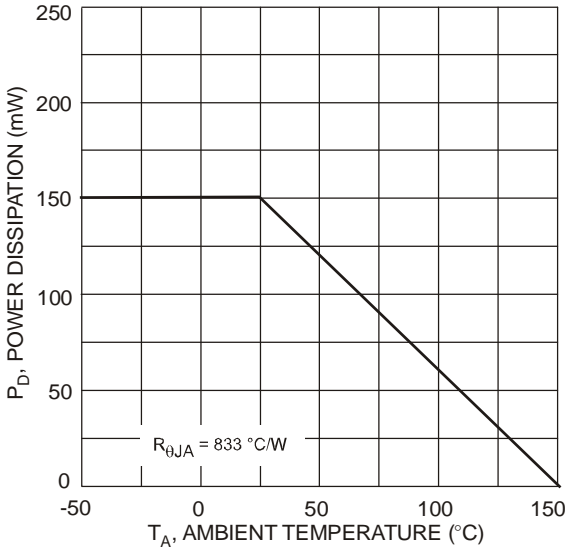


Fig. 1 Power Derating Curve, Total Package

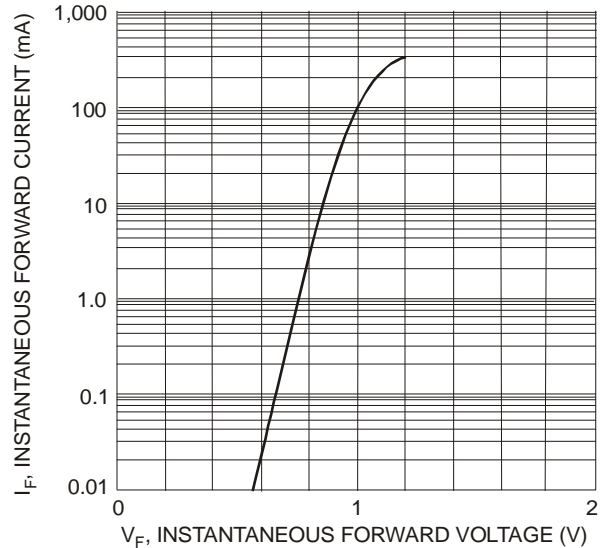


Fig. 2 Typical Forward Characteristics, Per Element

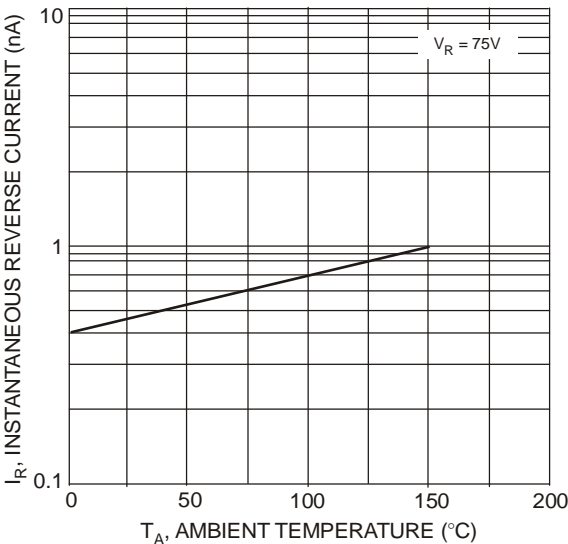


Fig. 3 Typical Reverse Characteristics, Per Element

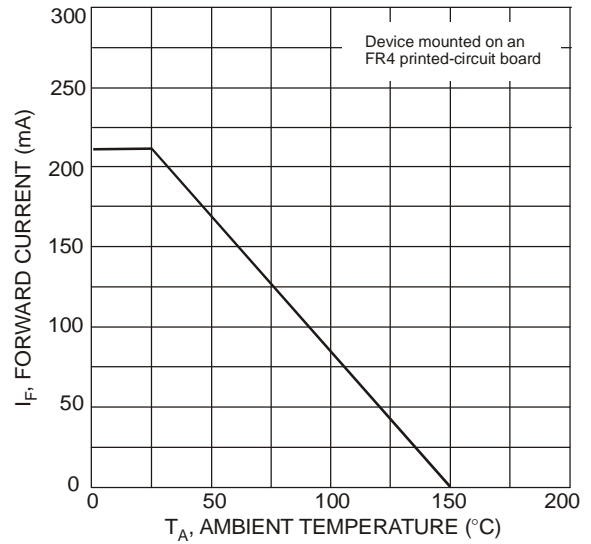


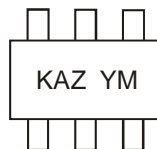
Fig. 4 Current Derating Curve, Per Element

**Ordering Information** (Note 6)

Part Number	Case	Packaging
BAS116V-7	SOT-563	3000/Tape & Reel

Notes: 6. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

**Marking Information**



KAZ = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: R = 2004)  
 M = Month (ex: 9 = September)

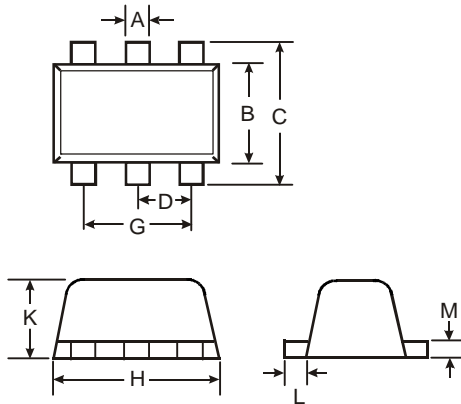
Date Code Key

Year	2004	2005	2006	2007	2008	2009	2010	2011	2012
Code	R	S	T	U	V	W	X	Y	Z

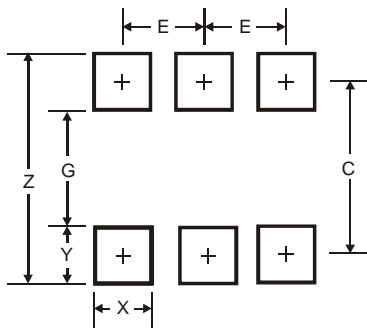
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Package Outline Dimensions**



SOT-563			
Dim	Min	Max	Typ
A	0.15	0.30	0.20
B	1.10	1.25	1.20
C	1.55	1.70	1.60
D	0.50		
G	0.90	1.10	1.00
H	1.50	1.70	1.60
K	0.55	0.60	0.60
L	0.10	0.30	0.20
M	0.10	0.18	0.11
All Dimensions in mm			

**Suggested Pad Layout**



Dimensions	Value (in mm)
Z	2.2
G	1.2
X	0.375
Y	0.5
C	1.7
E	0.5

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